

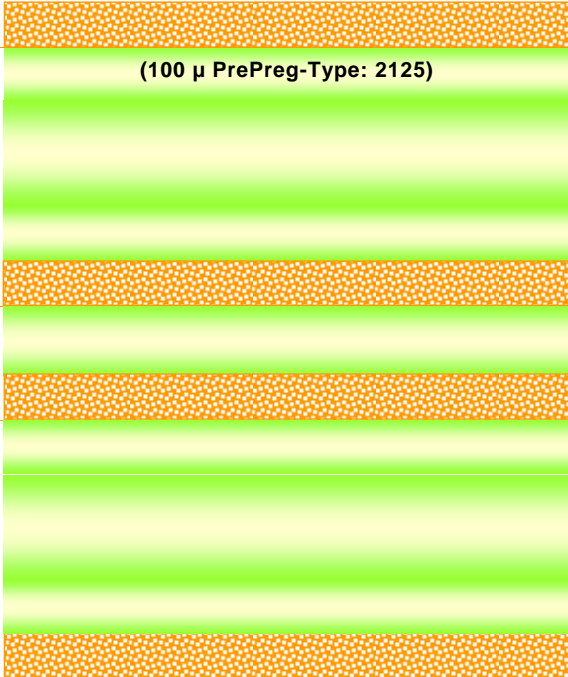
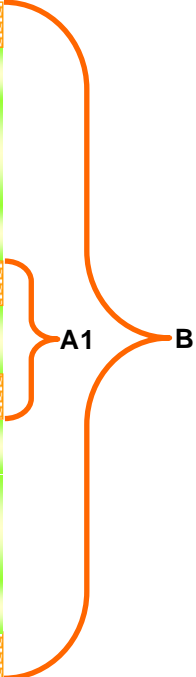
**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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**04 160 FR4 55 L41.00\_20.35 P10 S1**

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**04\_160\_FR4\_55\_L41.00\_20.35\_p10\_s1**

Layers	in $\mu$	Material	Build-Up	Assembly
<b>Layer-1</b>	55 $\mu$	Copper		
	100 $\mu$	Prepreg		
	410 $\mu$	L-FR4		
	100 $\mu$	Prepreg		
<b>Layer-2</b>	35 $\mu$	Copper		
	200 $\mu$	L-FR4		
<b>Layer-3</b>	35 $\mu$	Copper		
	100 $\mu$	Prepreg		
	410 $\mu$	L-FR4		
	100 $\mu$	Prepreg		
<b>Layer-99</b>	55 $\mu$	Copper		

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